	Туре	Hits	Search Text	DBs	Time Stamp	Comments
1.	IS&R	432	(428/654).CCLS.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2001/03/20	
2	IS&R	432	(428/654).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/03/20 13:14	-
3	BRS	72	(copper or cu) and sludge and consumable ADJ (anode or anodes or electrode or electrodes)	HIS - DISPITE *	2004/03/25 10:39	
4	BRS	50	electrode or electrodes)) and (electroplate or	US-PGPUB;	2004/03/25 10:51	
5	BRS	3	(((copper or cu) and sludge and consumable ADJ (anode or anodes or electrodes)) and (electroplate or electroplating or electroplated)) and sludge ADJ formation	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/25 10:49	
6	BRS	2	electrode or electrodes)) and (electroplate or	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/25 10:50	
7	BRS	5	(((copper or cu) and sludge and consumable ADJ (anode or anodes or electrodes)) and (electroplate or electroplating or electroplated)) and reference ADJ electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/25 10:53	
8	BRS	24042	(copper or cu) and (tellurium or te)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/25 10:53	

	Error Definiti on	Errors
1		0
2	·	0
3		0
4		0
5		0
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	Туре	Hits	Search Text	DBs	Time Stamp	Comments
9	BRS	1	(((copper or cu) and (tellurium or te)) and consumable ADJ (anode or anodes or electrode or electrodes)) and sludge	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/25 10:54	
10	BRS	33	((copper or cu) and (tellurium or te)) and consumable ADJ (anode or anodes or electrode or electrodes)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/25 11:07	
11	BRS	1	copper ADJ (alloy or alloys) and (tellurium or te) and sludge and (electroplating or electroplate or electroplated)	USOCR	2004/03/25 11:12	
12	BRS	225	(420/550).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/25 11:17	
13	IS&R	49	(420/500).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/25 11:28	
14	IS&R	735	(204/292).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/25 12:42	
15	BRS	1208	(204/292 or 204/293).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/25 11:30	
16	BRS	2	((204/292 or 204/293).ccls.) and copper ADJ (alloy or alloys or materials) and tellurium	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/25 11:39	

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9	-	0
10		0
11		0
12		0
13		0
14	·	0
15		0
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	Туре	L #	Hits	Search Text	DBs	Time Stamp	Comme	Error Definition	E r r
1	BRS	L1	52	consumable ADJ (anode or electrode or anodes or electrodes) and reference ADJ electrode	USP AT; US- PGP UB; EPO; JPO; DER WEN	2004/03 /25 13:01			Ο
2	BRS	L2	5	1 and electroplating WITH cell	USP AT; US- PGP UB; EPO; JPO; DER WEN	2004/03 /25 13:24		·	0

	U	1	Document ID	Issue Date	Pag es	Title	Current OR	Current XRef
1			US 200301507 15 A1	2003081	23	Anode assembly and method of reducing sludge formation during electroplating	204/229.	205/292
2			US 200300297 26 A1	2003021	14	Apparatus and method of evaluating electroplating solutions and conditions	205/81	204/230.
3			US 6261433 B1	2001071	23	Electro-chemical deposition system and method of electroplating on substrates	205/96	204/230. 2; 204/230. 7; 204/260; 204/261; 204/272; 204/273; 204/275. 1; 204/297. 01; 204/297. 03; 205/123; 205/123; 205/123; 205/123; 205/123; 205/123; 205/123;
4			US 5403460 A	1995040 4	<i>c</i>	Method and apparatus for nickel electro-plating	204/252	
5		·	US 200301507 15 A	2003081 4	23	Reduction of sludge formation during electroplating of copper over substrate, by applying current between consumable anode comprising copper and substrate, so that consumable anode is at specific potential		

	Retriev al Classif	Inventor		С	P	2	3	4	5	Image Doc. Displayed	PT
1		Yahalom, Joseph et al.	⊠		. 🗆					US 20030150715	
2		Kovarsky, Nicolay et al.	×							US 20030029726	
3		Landau, Uziel	\boxtimes							US 6261433	
4		Sala, Beatrice et al.								US 5403460	
5		HAZAN, J et al.	X							US 20030150715	